Power Module Board Level Reliability Report (as of 8/22/2013)

Summary

<table>
<thead>
<tr>
<th>Test Name</th>
<th>Conditions</th>
<th>Duration</th>
<th># of Lots</th>
<th>Sample Size</th>
<th>Rejects</th>
</tr>
</thead>
<tbody>
<tr>
<td>TEMP CYCLE</td>
<td>-20C TO 100C</td>
<td>920</td>
<td>1</td>
<td>10 (note 1)</td>
<td>0</td>
</tr>
<tr>
<td>TEMP CYCLE</td>
<td>-40C TO 125C</td>
<td>5000</td>
<td>1</td>
<td>9 (note 2)</td>
<td>0 (note 3)</td>
</tr>
<tr>
<td>TEMP CYCLE</td>
<td>-40C TO 125C</td>
<td>2000</td>
<td>1</td>
<td>45 (note 4)</td>
<td>0</td>
</tr>
<tr>
<td>TEMP CYCLE</td>
<td>-40C TO 125C</td>
<td>2000</td>
<td>1</td>
<td>44 (note 5)</td>
<td>0</td>
</tr>
<tr>
<td>TEMP CYCLE</td>
<td>-40C TO 125C</td>
<td>2000</td>
<td>1</td>
<td>16 (note 6)</td>
<td>0</td>
</tr>
<tr>
<td>TEMP CYCLE</td>
<td>-40C TO 125C</td>
<td>2000</td>
<td>1</td>
<td>16 (note 7)</td>
<td>0</td>
</tr>
</tbody>
</table>

Notes:
1) 15x15x2.2 QFN body size. 2 functional modules per board. Assembled using 63/37 Sn/Pb solder paste
2) 15x15x3.5 QFN body size. 1 functional modules per board. Assembled using 63/37 Sn/Pb solder paste
3) 1 reject detected at 2000 cycles – not due to board level solder joint failure.
4) 11.45x17.2x2.5 HDA body size. 1 daisy chain modules per board. Assembled using SAC 305 Pb free solder paste.
5) 11.45x17.2x2.5 HDA body size. 1 daisy chain modules per board. Assembled using 63/37 Sn/Pb solder paste.
6) 15x15x2.2 QFN body size. 2 functional modules per 12 layer board. Assembled using 63/37 Sn/Pb solder paste
7) 15x15x3.5 QFN body size. 2 functional modules per 12 layer board. Assembled using 63/37 Sn/Pb solder paste

For additional information, please contact

Address:
Intersil Corporation
Reliability Engineering
PO Box 65004 M/S 58-098
Palm Bay, FL 32906

Email: reports@rel.intersil.com
Phone: (321) 724-7437
Fax: (321) 729-5560